

PACKAGE FOR A SEMICONDUCTOR LIGHT EMITTING DEVICE

ABSTRACT OF THE DISCLOSURE

A semiconductor light emitting device package includes a substrate with a core and a copper layer overlying the core. The light emitting device is connected to the substrate directly or indirectly through a wiring substrate. The core of the substrate may be, for example, ceramic, Al_2O_3 , AlN, alumina, silicon nitride, or a printed circuit board. The copper layer may be bonded to the core by a process such as direct bonding of copper or active metal brazing.